

SOT1959-1

plastic thermal enhanced ultra thin quad flat package; no leads; 18 terminals; 0.4 mm pitch, 2.6 mm x 2.6 mm x 0.55 mm body

15 March 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HUQFN18
Package style descriptive code	HUQFN (thermal enhanced ultra thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	01-03-2019
Manufacturer package code	98ASA01174D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	2.6	-	mm
package width	-	2.6	-	mm
package height	-	0.55	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	18	-	



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2 Package outline

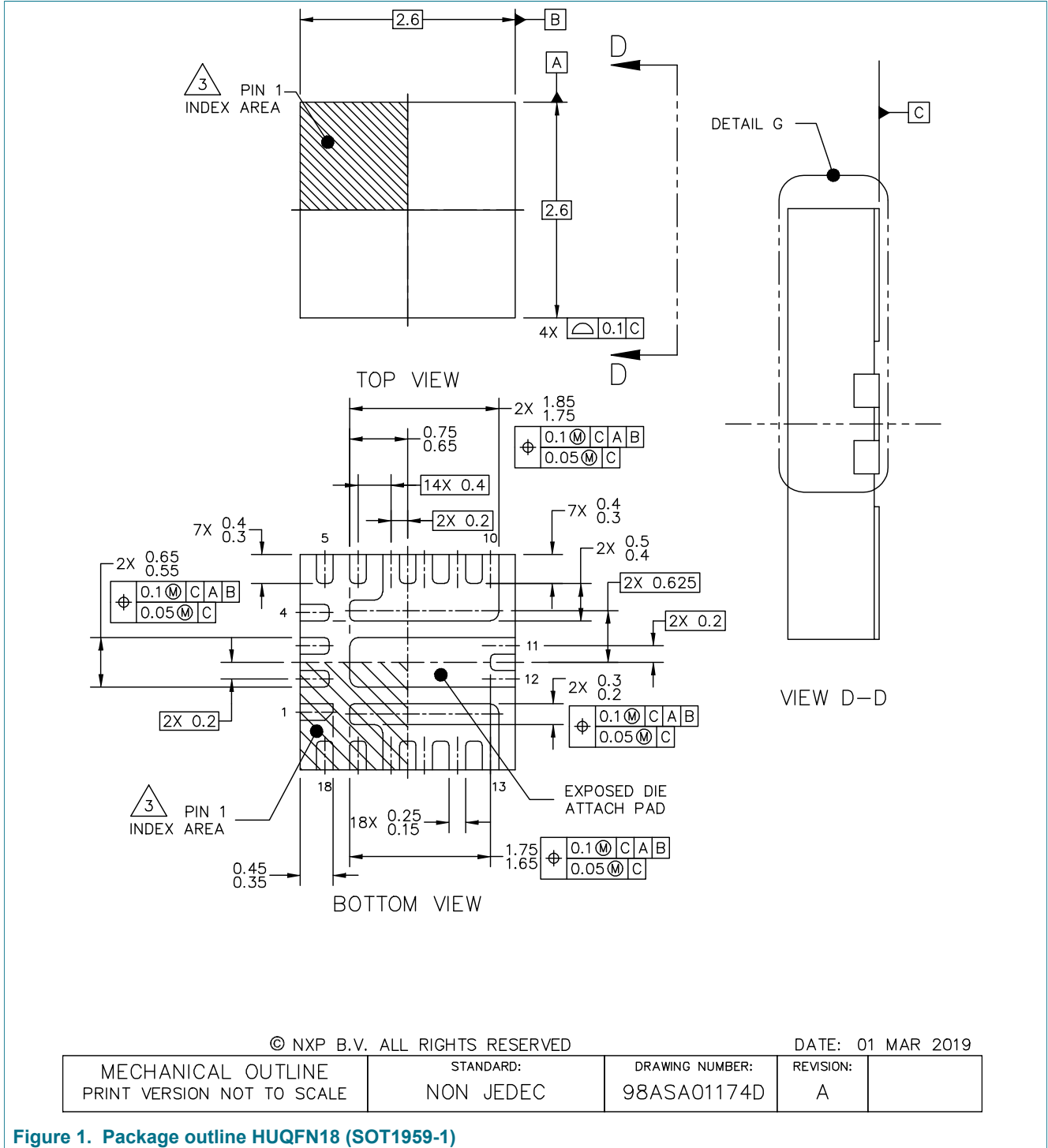


Figure 1. Package outline HUQFN18 (SOT1959-1)

plastic thermal enhanced ultra thin quad flat package; no leads; 18 terminals; 0.4 mm pitch, 2.6 mm x 2.6 mm x 0.55 mm body

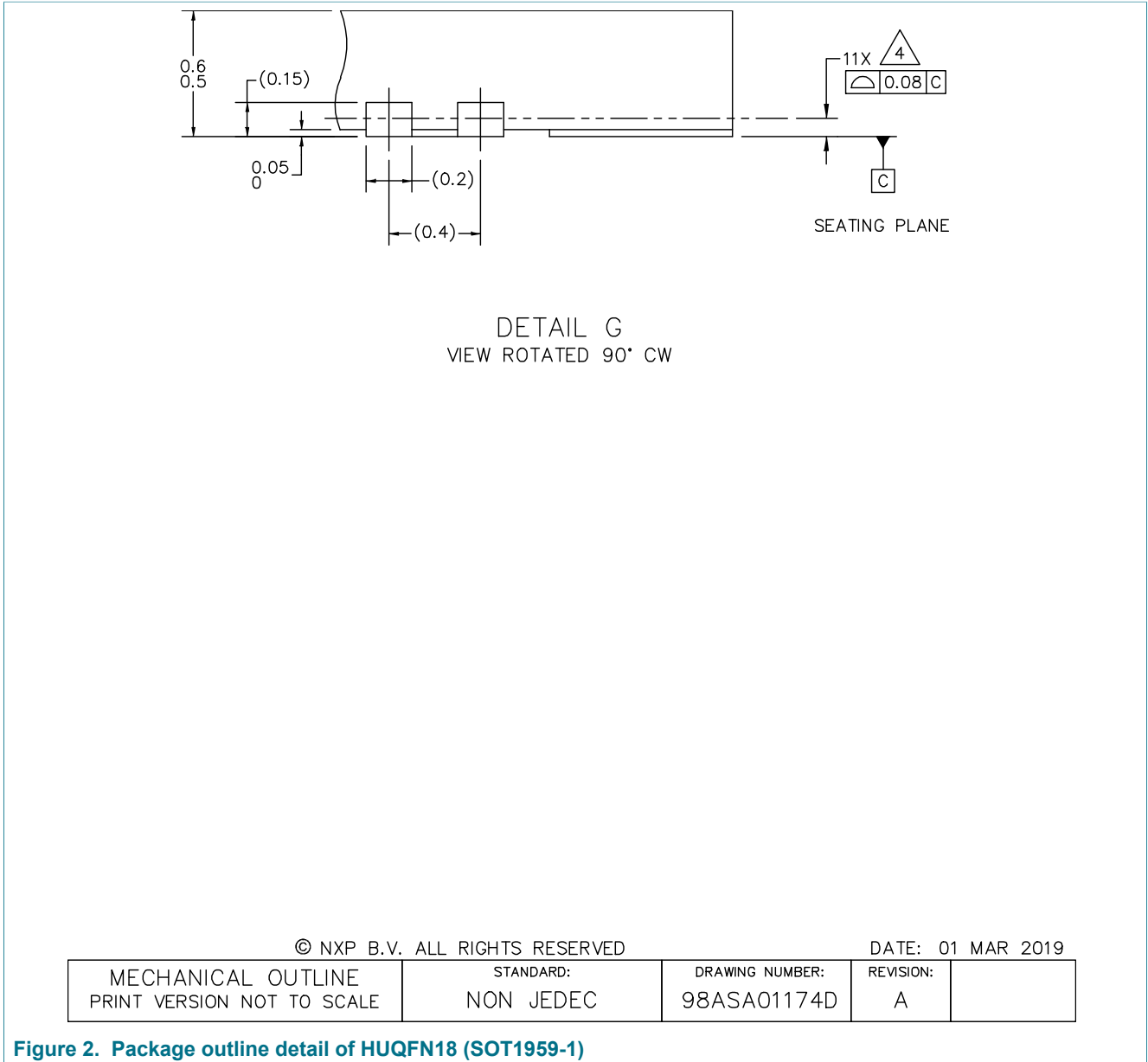


Figure 2. Package outline detail of HUQFN18 (SOT1959-1)

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3 Soldering

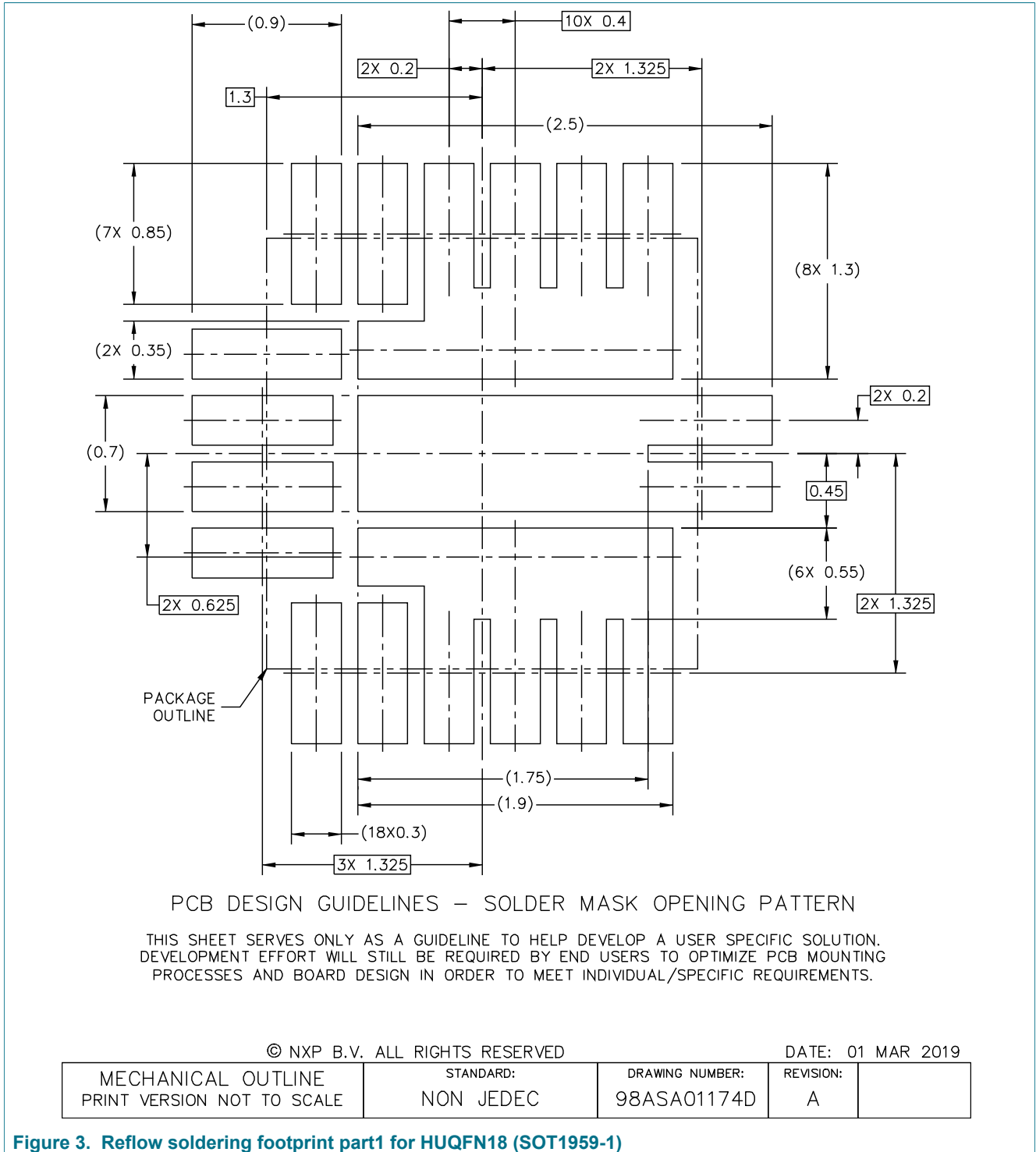
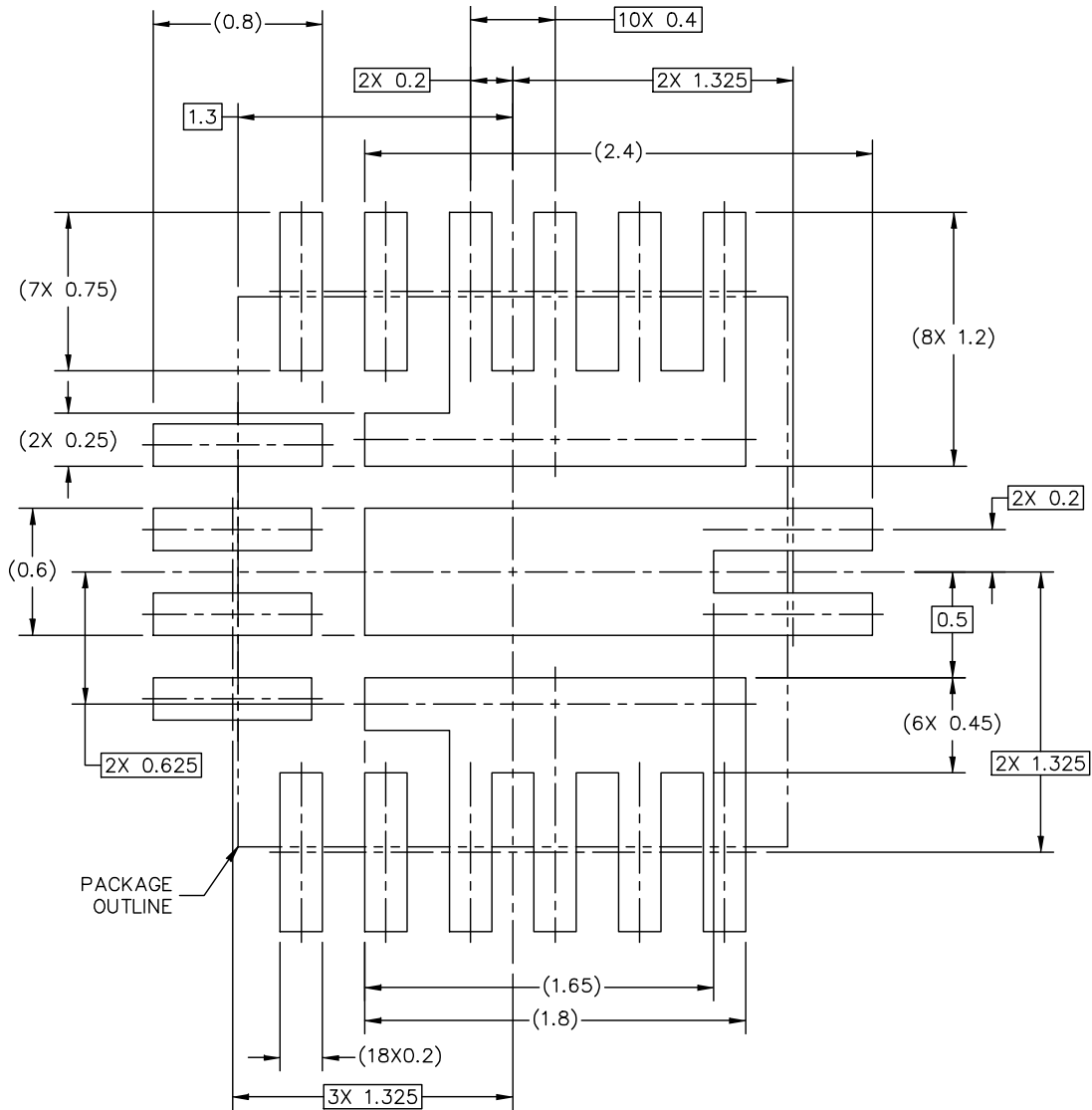


Figure 3. Reflow soldering footprint part1 for HUQFN18 (SOT1959-1)

plastic thermal enhanced ultra thin quad flat package; no leads; 18 terminals; 0.4 mm pitch, 2.6 mm x 2.6 mm x 0.55 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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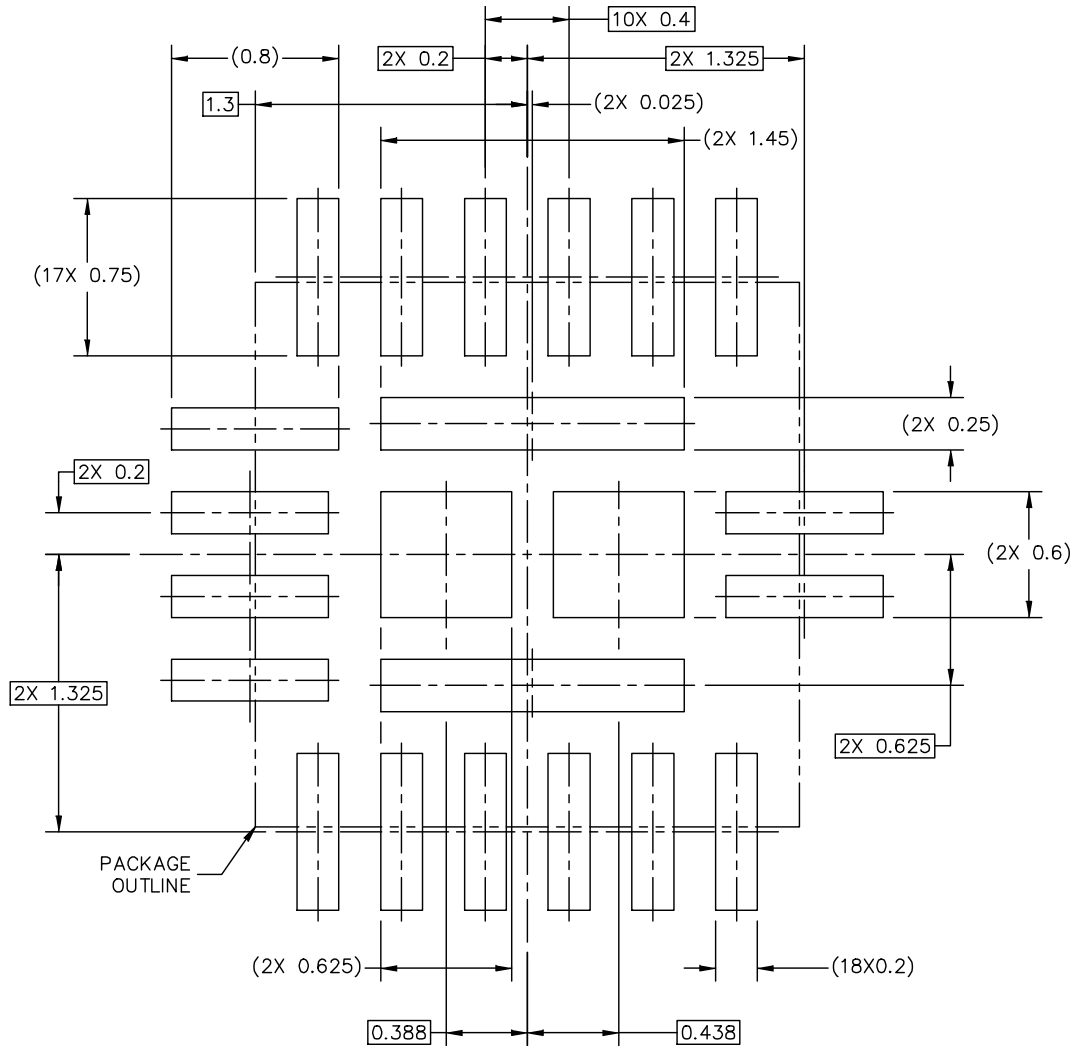
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Figure 4. Reflow soldering footprint part2 for HUQFN18 (SOT1959-1)

plastic thermal enhanced ultra thin quad flat package; no leads; 18 terminals; 0.4 mm pitch, 2.6 mm x 2.6 mm x 0.55 mm body



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HUQFN18 (SOT1959-1)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN ONE CONFIGURATION MAY VARY.
4. COPLANARITY APPLIES TO ALL LEADS, FUSED LEADS AND EXPOSED PAD ON BOTTOM SIDE.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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Figure 6. Package outline note of HUQFN18 (SOT1959-1)

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4 Legal information

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